



1PW 2823

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re PATENT APPLICATION of

Makoto TERUI et al.

Group Art Unit: 2823

Serial No: 10/717,934

Examiner: Brewster, William M

Filed: November 21, 2003

For: METHOD FOR FABRICATING A SEMICONDUCTOR DEVICE HAVING A
HEAT SPREADING LAYER

RESPONSE TO ELECTION/RESTRICTION REQUIREMENT

U.S. Patent and Trademark Office
Customer Service Window
Randolph Building
401 Dulany Street
Alexandria VA 22314

Sir:

In response to the Office Action of December 29, 2004, Applicants elect Species 1, claims 1-3, 6: forming a heat spreading material on the second surface of the semiconductor wafer and then after the spreading, separating the die. Claims 1 and 6 are generic.

Respectfully submitted,

VOLENTINE FRANCOS & WHITT, PLLC


Adam C. Volentine
Registration No. 33,289

One Freedom Square
11951 Freedom Drive, Suite 1260
Reston VA 21090
Tel. (703) 715-0870
Fax (703) 715-0877

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